

1 TITLE OF THE INVENTION

Liquid Jet Recording Head and substrate therefor.

BACKGROUND OF THE INVENTION

5 Field of the Invention

This invention relates to a liquid jet recording head which ejects liquid to produce flying liquid droplets to record, and to a substrate therefor.

Description of the Prior Art

10 Ink jet recording methods (liquid jet recording methods) have recently attracted attention since noise upon recording is very little and a high speed recording is possible, and further, the recording can be made on plain paper without any special treatment such as fixation.

15 Among them, for example, a liquid jet recording method disclosed in Japanese Patent Laid-open No. 51837/1979 and German Patent Laid-open (DOLS) No. 2843064 is different from other liquid jet recording methods in point that heat energy is applied to liquid to produce a driving
20 force for ejecting liquid droplets.

That is, the above-mentioned recording method comprises applying heat energy to a liquid to cause an abrupt increase in the volume of the liquid, ejecting the liquid from the orifice at the front of the recording head
25 to form flying liquid droplets and attaching the droplets to a record receiving member to effect recording.

1 In particular, the liquid jet recording method
disclosed in DOLS 2843064 cannot be only effectively
suitable for so-called "drop-on-demand" recording methods,
but also enables to realize easily a high density multi-
5 orifice recording head of a full-line type, and therefore,
images of high resolution and high quality can be produced
at a high speed.

 The recording head portion of an apparatus used for
the above-mentioned recording method comprises a liquid
10 ejecting portion constituted of an orifice for ejecting
liquid and a liquid flow path containing, as a part of the
construction, a heat actuating portion communicated with
the orifice and applying heat energy for ejecting liquid
droplets to the liquid, and an electrothermal transducer
15 for generating heat energy.

 The electrothermal transducer is provided with a
pair of electrodes formed on a support and a resistive
heater layer connected to the electrodes and having a
region generating heat (heat generating portion) between
20 the electrodes.

 A typical embodiment of the structure of such
liquid jet recording head is shown in FIG. 1A and FIG. 1B.

 FIG. 1A is a partial front view of the liquid
jet recording head viewed from the orifice side, and
25 FIG. 1B is a partial cross-sectional view taken along
the dot and dash line XY of FIG. 1A.

 Recording head 100 is constituted of orifice 104

1 and liquid ejecting portion 105 formed by bonding the
surface of substrate 102 provided with electrothermal
transducer to a grooved plate 103 having a predeter-
mined number of grooves having a predetermined width and
5 depth at a predetermined line density such that the
grooved plate covers the substrate. In FIG. 1, the
recording head has a plurality of orifices 104, but the
present invention is not limited to such an embodiment
and a recording head having a single orifice is also
10 within the scope of the present invention.

Liquid ejecting portion 105 has orifice 104
ejecting liquid at the end and heat actuating portion
106 where heat energy generated by electrothermal trans-
ducer is applied to liquid to form a bubble and an
15 abrupt state change due to expansion and shrinkage of
the volume occurs.

Heat actuating portion 106 is located above
heat generating portion 107 of electrothermal transducer
and a heat actuating surface 108 where heat gener-
20 ating portion 107 contacts the liquid is the bottom
surface of the heat actuating portion 106.

Heat generating portion 107 is constituted of
resistive heater layer 110 provided on lower layer 109
formed in substrate and upper layer 111 provided on
25 resistive heater layer 110. Electrodes 112 and 113 are
provided on the surface of resistive heater layer 110 for
flowing electric current to the layer 110 to generate heat.

1 Electrode 113 is a selection electrode for selecting the
heat generating portion of each liquid ejecting portion to
generate heat, and electrode 112 is an electrode common to
heat generating portions of liquid ejecting portions and is
5 provided along the liquid flow path of each liquid ejecting
portion.

Upper layer 111 serves to protect chemically and
physically resistive heater layer 110 from the liquid at
the heat generating portion 107 by isolating resistive
10 heater layer 110 from the liquid in the liquid flow path at
liquid ejecting portion 105 and further upper layer 111
prevents electrodes 112 and 113 from shortcircuiting
through the liquid. Thus, upper layer 111 serves to
protect resistive heater layer 110. Upper layer 111 also
15 serves to prevent electric leakage between adjacent elec-
trodes. In particular, it is important to prevent electric
leakage between selection electrodes and electrolytic
corrosion of electrodes caused by electric current flowing
in an electrode resulting from contact of an electrode
20 under the liquid flow path with the liquid which happens by
some cause. Therefore, such an upper layer 111 having a
protective function is provided on at least an electrode
which is disposed under a liquid flow path.

The upper layer is required to have various proper-
25 ties depending on the position to be disposed. That is,
for example, the following characteristics are required at
heat generating portion 107:

- 1) heat resistance,
- 2) liquid resistance,
- 3) liquid penetration preventing property,
- 4) thermal conductivity,
- 5) oxidation preventing property,
- 6) insulating property, and
- 7) breakage preventing property.

At portions other than heat generating portion 107, sufficiently high liquid penetration preventing property, liquid resistance and breakage preventing property are required though the resisting property to thermal conditions is not required to be so good.

However, at present there is not any material for constituting the upper layer capable of sufficiently satisfying all the characteristics 1) - 7) as mentioned above. It is the present status that some of the conditions 1) - 7) are not severely requested.

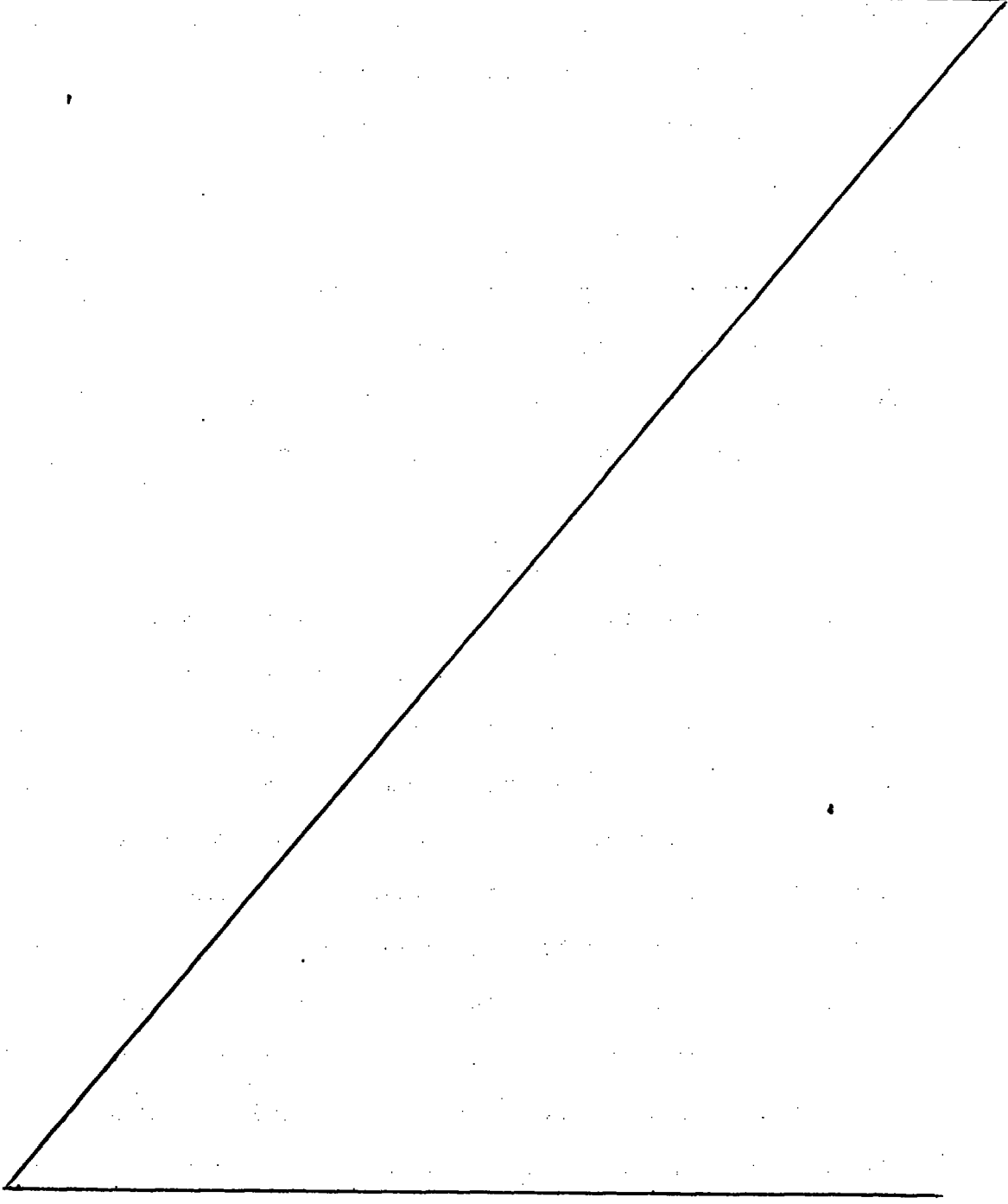
Apart from the above, in the case of a liquid jet recording head of a multi-orifice type, since a number of fine electrothermal transducers are formed on the substrate simultaneously, formation of each layer of the substrate and removal of a part of the formed layer are repeated, and as a result, the surface on which each layer in the upper layer is to be formed becomes a fine uneven surface having step edge portions, and therefore, the step coverage property of the layers in the upper layer at the step edge portions becomes important. In other words, when the step coverage

1 property at the step edge portions is poor, penetration of
the liquid occurs at the portions and causes electrolytic
corrosion or dielectric breakdown. Further, when the
formed upper layer suffers the formation of defects upon
5 fabrication with a considerable probability, penetration of
liquid occurs through the defect portion resulting in
shortening the life of the electrothermal transducer to a
great extent.

In view of the foregoing, it is required that the
10 upper layer has a good step coverage property at the step
edge, defects such as pinholes and the like occur in the
formed layer with only a low probability and even if the
defects are formed, the number of defects is negligibly
small or less.

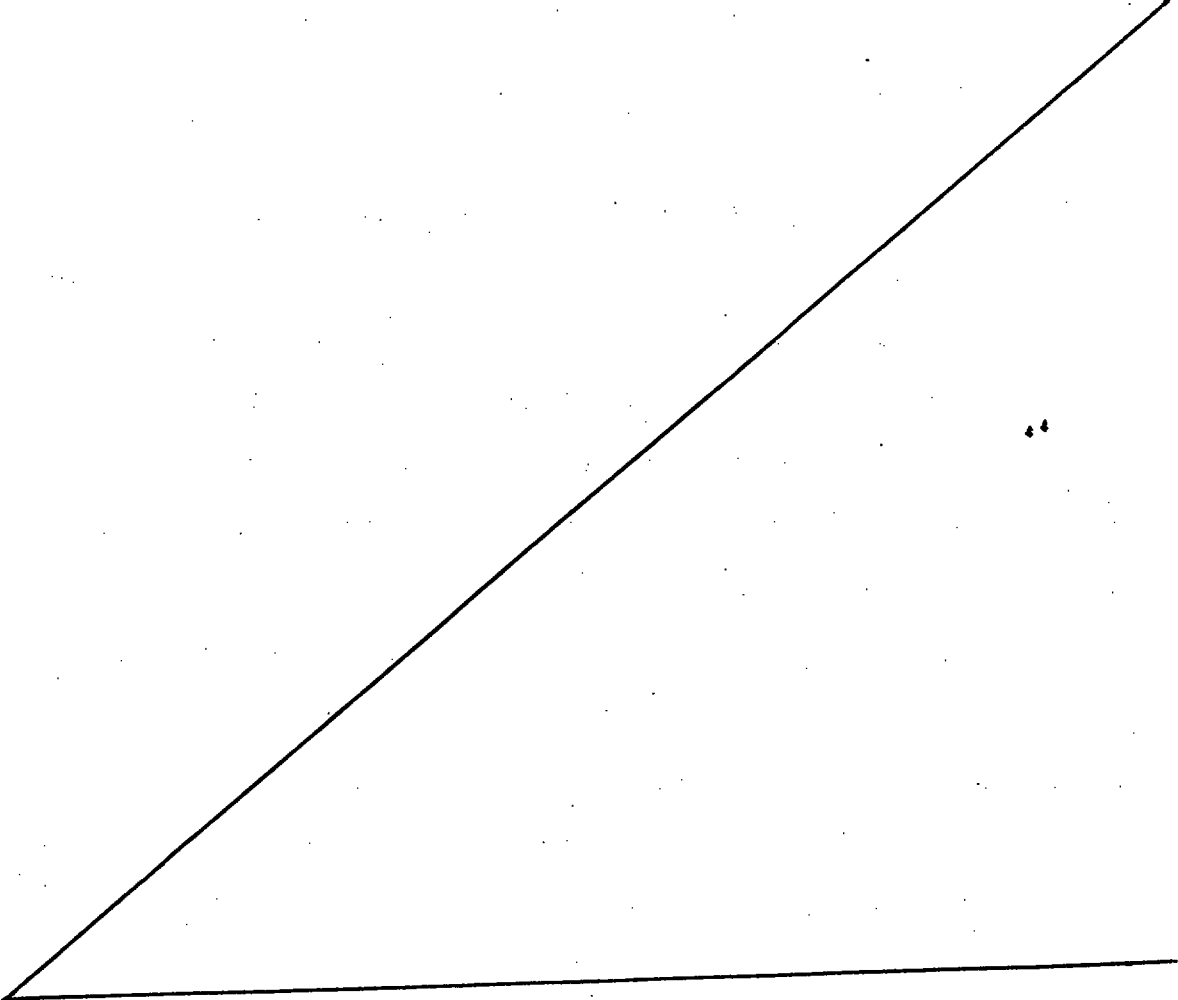
15 In order to satisfy those requisites, heretofore
the upper layer has been produced by laminating the first
protective layer composed of an inorganic insulating material
and the second protective layer composed of an organic
material, or the first protective layer is constituted of
20 two layers, that is, an under layer composed of an inorganic
insulating material and an above layer composed of an in-
organic material of high toughness, relatively excellent
mechanical strength and having adhesion and cohesion to
the first protective layer and the second protective layer,
25 such as metals and the like, or the third protective layer
composed of an inorganic material such as metals and the
like overlies the second protective layer.

5 However, it is very difficult that the upper layer having no defects is formed by the above-mentioned process. The liquid jet recording head satisfying all the requirements and having totally excellent durability for use has not yet been provided.



In accordance with one aspect of the present invention, there is provided a substrate for a liquid jet recording head, the substrate carrying an electrode arrangement in the form of a u-shape with a break being formed in the u-shape to provide a pair of electrodes, and a resistive heater layer coating and covering at least part of each electrode and bridging the break between the electrodes to form an electrothermal transducer.

In accordance with another aspect of the present invention, there is provided a liquid jet recording head having a substrate according to the ^{first mentioned} [third] aspect of the invention. _____



1 BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1A and B refer to a conventional liquid jet recording head, FIG. 1A shown schematically a partial front view and FIG. 1B is a partial cross-sectional view taken
5 along a dot and dash line XY in FIG. 1A;

FIG. 2A and B refer to a liquid jet recording head according to the present invention, FIG. 2A shows schemati-
cally a partial front view, FIG. 2B is a partial cross-sectional view taken along a dot and dash line AA' in FIG. 2A;

10 FIGS. 3A, B and C are partial cross-sectional views taken along a dot and dash line AA' in FIG. 2A to show embodiments of the present invention;

FIGS. 4A, B and C are front views of embodiments of the present invention.

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DESCRIPTION OF THE PREFERRED EMBODIMENTS

A liquid jet recording head of the present invention will be described in detail referring to the drawings.

FIG. 2A is a partial front view of a liquid jet
20 recording head of the present invention viewed from the orifice side for explaining the main part of the structure of a preferable embodiment of the present invention and FIG. 2B shows a partial cross-sectional view taken along a dot and dash line in FIG. 2A. FIG. 2A and FIG. 2B
25 correspond to FIG. 1A and FIG. 1B, respectively.

Liquid jet recording head 200 is mainly constituted of a substrate 202 provided with a predetermined number of

1 electrothermal transducer for liquid jet recording where
heat is used for liquid ejection and a grooved plate 203
having a predetermined number of grooves corresponding to
the above-mentioned electrothermal transducers 204 - 1,
5 204 - 2 and 204 - 3 are liquid flow paths.

Substrate 202 and grooved plate 203 are bonded at
predetermined portions with adhesives or the like to form
liquid flow path 215 defined by the portion of substrate
202 where electrothermal transducer is provided and the
10 groove of grooved plate 203, and the liquid flow path 215
has heat actuating portion 206.

Substrate 202 is constituted of support 214 composed
of silicon, glass, ceramics or the like, lower layer 209
overlying support 206 and composed of SiO_2 or the like,
15 common electrode 212, selection electrode 213, resistive
heater layer 210 overlying each electrodes, and upper layer
211 overlying resistive heater layer 210.

The electrothermal transducer comprises heat
generating portion 207 as the main portion. The heat
20 generating portion 207 is constituted of support 214, lower
layer 209, resistive heater layer 210 and upper layer 211
successively formed. The surface of upper layer 211 (heat
actuating surface 208) directly contacts the liquid filled
in liquid flow path 215.

25 Upper layer 211 is constituted of inorganic materials
relatively excellent in electric insulating property, thermal
conductivity, and heat resistance, for example, inorganic

1 oxides such as SiO_2 and the like and inorganic nitrides such
as Si_3N_4 and the like.

As described above, the upper layer may be formed
with a combination of the first protective layer, the
5 second protective layer, the third protective layer.

As materials constituting the first protective layer,
there are preferably used inorganic insulating materials
relatively excellent in thermal conductivity and heat
resistance, for example, inorganic oxides such as SiO_2 and
10 the like, transition metal oxides such as titanium oxide,
vanadium oxide, niobium oxide, molybdenum oxide, tantalum
oxide, tungsten oxide, chromium oxide, zirconium oxide,
hafnium oxide, lanthanum oxide, yttrium oxide, manganese
oxide and the like, metal oxides such as aluminum oxide,
15 calcium oxide, strontium oxide, barium oxide, silicon oxide
and the like and composites thereof, high resistance
nitrides such as silicon nitride, aluminum nitride, boron
nitride, tantalum nitride and the like and composites of
these oxides and nitrides, and thin film materials, for
20 example, semiconductors comprising amorphous silicon,
amorphous selenium and the like which have low resistance
as bulk, but may be made to have high resistance by a
sputtering method, a CVD method, a vapor deposition method,
a gas phase reaction method, a liquid coating method or the
25 like.

As materials used for forming the third protective
layer, in addition to Ta as mentioned above, there may be

1 mentioned the elements of Group IIIa of the periodic Table
such as Sc, Y and the like, the elements of Group IVa such
as Ti, Zr, Hf and the like, the elements of Group Va such
as V, Nb and the like, the elements of the Group VIa such
5 as Cr, Mo, W and the like, the elements of Group VIII such
as Fe, Co, Ni and the like, alloys of the above-mentioned
metals such as Ti-Ni, Ta-W, Ta-Mo-Ni, Ni-Cr, Fe-Co, Ti-W,
Fe-Ti, Fe-Ni, Fe-Cr, Fe-Ni-Cr and the like, borides of the
above-mentioned metals such as Ti-B, Ta-B, Hf-B, W-B and
10 the like, carbides of the above-mentioned metals such as
Ti-C, Zr-C, V-C, Ta-C, Mo-C, Cr-C and the like, silicides
of the above-mentioned metals such as Mo-Si, W-Si, Ta-Si
and the like, nitrides of the above-mentioned metals such
as Ti-N, Nb-N, Ta-N and the like. Using these materials,
15 the third protective layer may be formed by the procedure
such as a vapor deposition method, a sputtering method, a
CVD method and the like. The third protective layer may
be composed of the above materials, alone or in combination.

The second protective layer is composed of an organic
20 insulating material which is excellent in prevention of
liquid penetration and liquid resistance, and further has
preferably the following characteristics:

- (1) Good film shapeability,
- (2) Dense structure and free from pinholes,
- (3) Not swelled with and not dissolved in the ink,
- (4) High insulating property when film-shaped,
- (5) High heat resistance,

1 and the like.

As the organic materials, there may also be used, for example, silicone resin, fluorine resin, aromatic polyamide, addition polymerization type polyimide, poly-
5 benzimidazole, metal chelate polymer, titanate acid ester, epoxy resin, phthalic resin, thermosetting phenolic resin, p-vinylphenolic resin, Zirox resin, triazine resin, BT resin (addition polymerized resin of triazine resin and bismaleimide) or the like. Alternatively, it is also
10 possible to form the second protective layer by vapor deposition of polyxylylene resin and derivatives thereof.

Further, the second protective layer may also be formed by film shaping according to a plasma polymerization using various organic monomers such as thiourea, thio-
15 acetamide, vinyl ferrocene, 1,3,5-trichlorobenzene, chlorobenzene, styrene, ferrocene, pyrrole, naphthalene, pentamethylbenzene, nitrotoluene, acrylonitrile, diphenyl selenide, p-toluidine, p-xylene, N,N-dimethyl-p-toluidine, toluene, aniline, diphenyl mercury, hexamethylbenzene,
20 malononitrile, tetracyanoethylene, thiophene, benzene-selenol, tetrafluoroethylene, ethylene, N-nitrosodiphenylamine, acetylene, 1,2,4-trichlorobenzene, propane and the like.

However, when a recording head of a high density
25 multi-orifice type is manufactured, apart from the above-mentioned organic materials, it is desirable to use organic materials capable of being very easily processed by a fine

1 photolithography as materials for forming the second protective layer.

As examples of the organic materials, there may be preferably used, for example, polyimidoisoindoloquinazo-
5 linedione (trade name; PIQ, produced by Hitachi Kasei Co., Japan), polyimide resin (trade name: PYRALIN, produced by Du Pont, U.S.A.), cyclized polybutadiene (trade name: JSR-CBR, CBR-M901, Japan Synthetic Rubber Co., Japan), Phtotonith (trade name: produced by Toray Co., Japan), other photo-
10 sensitive polyimide and the like.

As the material constituting resistive heater layer 210, there may be used most materials capable of generating heat as desired by flowing electric current.

However, it is desirable that the materials are
15 neither chemically changed by nor dissolved in the ink used and have high heat resistance.

As examples of the materials, there may be preferably used, for example, tantalum nitride, nichrome, silver-palladium alloy, silicon semiconductor, or a metal
20 such as hafnium, lanthanum, zirconium, titanium, tantalum, tungsten, molybdenum, niobium, chromium, vanadium and the like, alloys thereof, borides thereof or the like.

Even if the ink in the liquid flow path contacts the substrate through cracks and pinholes formed in upper
25 layer 211, these materials are passivated at the portion contacting the ink and a passive layer is formed. Therefore, the ink does not reach the electrode layer

1 and electrolytic corrosion does not occur. Thereby
durability for the liquid jet recording head is improved.

Using the above-mentioned material, the resistive
heater layer 210 may be formed by the procedure such as an
5 electron beam method, a sputtering method and the like.

As the materials for constituting electrodes 212
and 213, there may be effectively used most of conventional
electrode materials, and there are mentioned, for example,
Al, Ag, Au, Pt, Cu and the like. The electrodes may be
10 formed at a predetermined position with a predetermined
size, shape and thickness by means of vapor deposition or
the like.

Lower layer 209 is provided so as to control mainly
the transfer of heat generated at heat generating portion
15 207 to support 214. The construction material is selected
and the layer thickness is designed in such a way that the
heat generated at heat generating portion 207 flows more to
the heat actuating portion 206 side than to other portions
when heat energy is applied to the liquid at heat actuating
20 portion 206 while the heat remaining at heat generating
portion 207 flows rapidly to the support 214 side when the
electric current to electrothermal transducer is switched
off.

As the material for constituting lower layer 209,
25 there may be used inorganic materials represented by metal
oxides such as SiO_2 , zirconium oxide, tantalum oxide,
magnesium oxide and the like.

1 Support 214 is composed of silicon, glass, ceramics
or the like.

 As the materials for constituting the grooved plate
203 and the common liquid chamber provided at the upstream
5 portion of heat actuating portion 206, there may be used
most of the materials satisfying the following conditions:
i) the shape is hardly or not thermally affected during
fabricating the recording head or under the circumstance of
using the recording head; ii) a fine precise processing can
10 be applied thereto and the surface accuracy can be easily
obtained as desired; and iii) the resulting liquid paths can
be processed to permit the liquid to flow smoothly in the
paths.

 Representative materials for the above-mentioned
15 purpose are preferably ceramics, glass, metals, plastics,
silicon wafer and the like, and in particular, glass and
silicon wafer are more preferable since they are easily
processed, and have an appropriate degree of heat
resistance, coefficient of thermal expansion and thermal
20 conductivity. It is desired to apply to the outer surface
of the circumference of orifice 204 a water repellent
treatment where the liquid is aqueous and an oil repellent
treatment where the liquid is non-aqueous, so as to prevent
the liquid from leaking and flowing to the outside portion
25 of orifice 204.

 The said orifice may be formed by adhering a photo-
sensitive resin plate such as a dry film and the like to

1 substrate, forming a pattern by photolithography and then
adhering the ceiling plate.

As described above, resistive heater layer 210 may
be formed on the whole surface of electrodes 212 and 213 as
5 shown in FIG. 3A, or only on the surface of electrodes 212
and 213 under the liquid flow path 215 as shown in FIG. 3B.
Alternatively, in case that dissolution of electrodes can be
almost prevented by selecting appropriately the material of
the upper layer 211 or an appropriate structure of the
10 upper layer 211 composed of first protective layer 211-1
and second protective layer or third protective layer 211-2,
as shown in FIG. 3C, a sufficient effect can be obtained by
providing resistive heater layer 210 only on a limited
portion.

15 Further, the width of resistive heater layer 210 is
most preferably wider than widths of electrodes 212 and 213
as shown in FIG. 4A. However, as shown in FIG. 4B, it is
necessary only that the surface of the electrodes is almost coated
with resistive heater layer 210. Alternatively, the width
20 of resistive heater layer 210 at the heat actuating portion
may be narrower than that of the resistive heater layer
coating the electrode as shown in FIG. 4C.

The liquid jet recording head of the present
invention is illustrated by referring to the following
25 Example.

Example

Liquid jet recording heads of the present invention

1 as shown in FIG. 2, FIG. 3A and FIG. 4A were manufactured as shown below.

5 An SiO_2 film of 5 μm thick was formed by thermally oxidizing an Si wafer. On the SiO_2 film, Ti layer of 50 $\text{\AA}$ thick and Al layer of 5,000 $\text{\AA}$ thick were deposited successively by an electron beam deposition. By photolithographic steps, the electrode was patterned to form electrodes 212 and 213.

10 As the next step, a resistive heater layer composed of HfB_2 of 1500 $\text{\AA}$ thick was formed by sputtering and then, by photolithographic steps, a portion corresponding to the resistive heater layer was patterned with a resist, followed by etching a portion corresponding to heat actuating portion 207 to form resistive heater layer 210. Size of the heat
15 actuating surface was 30 μm in width and 150 μm in length.

Then, upper layer 111 composed of SiO_2 of 2.8 μm thick was deposited by a high rate sputtering.

Grooved plate 203 composed of glass was adhered on the predetermined place of the substrate fabricated as
20 described above. Size of liquid flow path 215 was 50 μm in width and 50 μm in height. The resulting liquid jet recording head (B_1) and a conventional liquid jet recording head (A) were investigated for the rate of a breakdown (the number of open wire/all segments) by applying a pulse-shaped
25 signal having 40 V, 10 μs in pulse width and 5 kHz in repetition frequency to an ink (pH4-9) maintained at 60°C. The results are as shown in Table 1. The liquid jet

1 recording head of the present invention has excellent durability and can keep, over a long time, the good initial property for forming droplets.

The heads B_2 and B_3 were similarly fabricated using
5 resistive heater layer 210 comprising TaN_2 or Ta and were investigated for the rate of breakdown. As shown in Table 1, the results indicate that the heads B_2 and B_3 have excellent durability and can keep the good initial property for forming
droplets over a long time.

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Table 1

15

Type of head		Constructive material		Rate of breakdown			
		Electrode	Resistive heating element	10^5	10^6	10^7	10^8
A		Al	HfB_2	5%	12%	32%	89%
B	1	Al	HfB_2	0%	1%	5%	21%
	2	Al	TaN_2	0%	0%	2%	17%
	3	Al	Ta	0%	0%	1%	17%

20

The said resistive heater layer may be coated on the whole surface of the electrode, only on a portion corresponding to the liquid flow path or only on the heat actuating portion and its vicinity. The coating portion may be determined in accordance with a combination with the upper layer.

25

Width of the resistive heater layer overlying the electrode is not critical as far as it can almost cover the electrode. The width on the heat actuating surface where

1 an electrode is not provided may be narrower than that at a
portion overlying the electrode. By constructing as
described above, a rise of temperature at the boundary
between the electrode and the resistive heater layer is
5 suppressed and a recording head having a higher reliability
can be provided.

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CLAIMS:

1. A substrate for a liquid jet recording head, the substrate carrying an electrode arrangement in the form of a u-shape with a break being formed in the u-shape to provide a pair of electrodes, and a resistive heater layer coating and covering at least part of each electrode and bridging the break between the electrodes to form an electrothermal transducer.

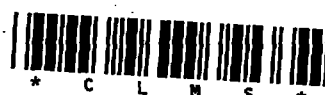
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2. A liquid jet recording head having a substrate carrying an electrode arrangement in the form of a u-shape with a break being formed in the u-shape to provide a pair of electrodes, and a resistive heater layer coating and covering at least part of each electrode and bridging the break between the electrodes to form an electrothermal transducer.

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3. A liquid jet recording head comprising a substrate as claimed in claim 1 and a member which, with the substrate, defines a liquid flow path extending past the electrothermal transducer to a discharge orifice.

20



4. A head according to claim 3, wherein the resistive heater layer is provided under the liquid flow path.

5 5. A substrate or head according to any preceding claim, wherein the width of the resistive heater layer is narrowed between the electrodes.

6. A substrate or head according to any preceding claim, wherein the substrate has further an upper layer.

7. A substrate or head according to claim 6, wherein the upper layer is composed of inorganic insulating material.

8. A substrate or head according to claim 6, wherein the upper layer is composed of inorganic insulating material, organic material and inorganic material.

9. A substrate or head as claimed in claim 6, wherein the upper layer comprises inorganic insulating material inorganic material or organic material provided on at least a part of the upper portion of the electrodes and inorganic insulating material



provided on at least a part of the resistive heater layer between the electrodes.

5 10. A substrate or head as claimed in any preceding claim, wherein the electrodes and the resistive heater layer are formed successively on the substrate.

10 11. A substrate or head as claimed in any preceding claim, wherein the electrode arrangement is shaped substantially as shown in any of Figures 4A to 4C of the accompanying drawings.

15 12. A liquid recording head or substrate therefor substantially as described in the description with reference to Figures 2 to 4 of the drawings.

